

*B<sup>1</sup> 307*  
*da*  
equipment, the frame being configured to support the installation of semiconductor processing equipment.

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*a<sup>6</sup>*  
8. (Amended) The support apparatus of Claim 1 further comprising flanges along inner edges of the frame to support raised flooring.

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9. (Amended) The support apparatus of Claim 7 further comprising flanges along inner edges of the frame to support raised flooring.

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*a<sup>7</sup>*  
11. (Amended) The support apparatus of Claim 10 wherein the at least one facilities connection locator provides a plurality of connection points for connecting site facilities to the semiconductor processing equipment.

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*a<sup>8</sup>*  
13. (Amended) The support apparatus of Claim 1 further comprising a plurality of seismic braces each affixed to one of the support legs and adapted to fix to a piece of semiconductor processing equipment to be supported by the support apparatus.

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*a<sup>9</sup>*  
20. (Amended) Support apparatus for an installation of semiconductor processing equipment having a bottom outline and a plurality of load-bearing mounting feet disposed along the equipment's bottom outline comprising:  
a plurality of support legs including at least one support leg aligned to each one of the plurality of load-bearing mounting feet; and  
a frame disposed on the plurality of support legs, the frame being configured to support the installation of semiconductor processing equipment.

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Add new claims 21 and 22 as follows.

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21. (New) Support apparatus for an installation of semiconductor processing equipment having a plurality of load-bearing mounting feet at a bottom of the semiconductor processing equipment comprising:

a plurality of support legs including at least one support leg aligned to each one of the plurality of load-bearing feet; and

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a frame disposed on the plurality of support legs, the frame being configured to support the installation of semiconductor processing equipment.

22. (New) The support apparatus of claim 21, wherein the frame has a frame outline which substantially duplicates a bottom outline of the semiconductor processing equipment.

#### REMARKS

Applicants hereby affirm election for prosecution of Group I, claims 1-13 and 20.

Responsive to the drawing objection, a Request for Approval of Drawing Change accompanies this Amendment for the purpose of adding a new FIG. 4A to show outer and inner flanges. It is believed that the new drawing does not introduce new matter, in view of the support for the outer and inner flanges found at page 7, line 36 to page 8, line 2 of the specification. In addition, the specification has been amended to refer to FIG. 4A, including a reference in the Brief Description of the Drawings section.

Claims 1-13 and 20-22 are now in this application, non-elected claims 14-19 having been canceled, and new